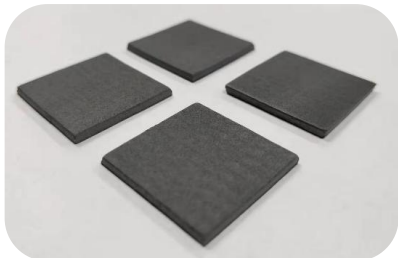




## HCF-14

### 【Thermal Gap Filler】

## DATA SHEET



#### FEATURES:

- Soft surface, good compressibility
- Low thermal resistance
- Application under low pressure
- Good thermal stability

#### APPLICATIONS:

- Base station
- Chip
- Large server
- Data processing center

This series of products are environmentally compliant with RoHS 2.0, halogen, and REACH standards.

**STORAGE CONDITIONS:** Storage in the darkness

**STORAGE TEMPERATURE:**  $\leq 30^{\circ}\text{C}$

**STORAGE HUMIDITY:**  $\leq 70\%$

#### SHELF LIFE:

Under storage conditions: 2 year

Non storage conditions: 6 months.

HFC **HCF-14** is a carbon fiber thermal pad with high thermal conductivity and low thermal resistance. The thermal pad uses advanced arrangement technology to make the carbon fibers evenly and vertically distributed in the silicone matrix, greatly improving the efficiency of heat transfer. This carbon fiber thermal pad maintains high thermal conductivity and high flexibility of silicone material. It can work normally under extremely low stress conditions. It is mainly used to solve the high heat flux devices' solutions such as large servers and chips.

#### PROPERTIES

Items	Parameter	Test Method
Color	Gray black	Visual
Standard Size (mm)	120*120	ASTM D 5947
Thickness (mm)	0.5~3( $\pm 10\%$ )	ASTM D 374
Hardness (Shore 00)	55( $\pm 10$ )	ASTM D 2240
Density (g/cc)	2.0( $\pm 0.2$ )	ASTM D 792
Operating Temperature ( $^{\circ}\text{C}$ )	-40~125	IEC 60068-2-14

#### THERMAL CHARACTERISTIC

Thermal Conductivity ( $\text{W/m}\cdot\text{K}$ )	25.0( $\pm 5$ )	ASTM D 5470
Thermal Resistance ( $^{\circ}\text{C}\cdot\text{in}^2/\text{W}$ )	$\leq 0.18$ (@20psi/2mm)	ASTM D 5470

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